

ABSTRACT

Provided in the embodiments of the present disclosure are an immersion-type liquid-cooling device and an immersion-type liquid-cooling system. The immersion-type liquid-cooling device comprises: a cooling tank, which is adapted to accommodate a main cooling liquid in a sealed manner, so as to immerse, in the main cooling liquid, an electronic device needing to be cooled; a main heat dissipation apparatus, which is attached to the cooling tank, and comprises an inner cavity enclosed by a housing, and a main circulating component and heat exchanger accommodated in the inner cavity, wherein the inner cavity is in communication with the cooling tank in a sealed manner, and the main circulating component is adapted to circulate the main cooling liquid between the cooling tank and the exterior of the heat exchanger; and a cold source interface, which is coupled to the main heat dissipation apparatus, and is configured to allow an auxiliary cooling liquid to circulate between an external cold source and the interior of the heat exchanger, such that the auxiliary cooling liquid exchanges heat with the main cooling liquid at the heat exchanger. By using a modular liquid-cooling device, the deployment of a liquid-cooling system of a data center is significantly simplified, and the deployment of the liquid-cooling system is more flexible, thereby significantly improving the deployment efficiency.